

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau

(43) International Publication Date
16 March 2023 (16.03.2023)



(10) International Publication Number
WO 2023/038757 A1

(51) International Patent Classification:

H01L 23/00 (2006.01) H01L 23/498 (2006.01)
H01L 23/14 (2006.01)

(21) International Application Number:

PCT/US2022/040071

(22) International Filing Date:

11 August 2022 (11.08.2022)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

63/242,400 09 September 2021 (09.09.2021) US

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(81) Designated States (*unless otherwise indicated, for every
kind of national protection available*): AE, AG, AL, AM,
AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ,
CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM,
DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT,
HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE,
KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU,
LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA,
NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO,
RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH,
TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS,
ZA, ZM, ZW.

(84) Designated States (*unless otherwise indicated, for every
kind of regional protection available*): ARIPO (BW, GH,
GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, ST, SZ, TZ,

(54) Title: STIFFENER FRAME FOR SEMICONDUCTOR DEVICE PACKAGES

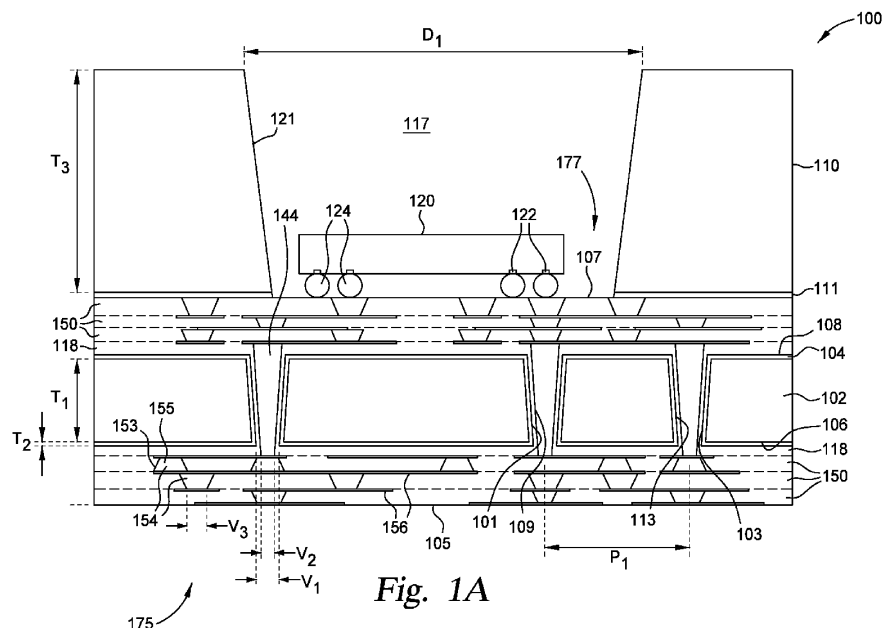


Fig. 1A

(57) Abstract: The present disclosure relates to semiconductor devices and methods of forming the same. More particularly, the present disclosure relates to semiconductor package devices having a stiffener framed formed thereon. The incorporation of the stiffener frame improves the structural integrity of the semiconductor package devices to mitigate warpage and/or collapse while simultaneously enabling utilization of thinner core substrates for improved signal integrity and power delivery between packaged devices.

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UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Published:

— *with international search report (Art. 21(3))*